

# FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16971

Generic Copy

### Issue Date: 12-Feb-2013

<u>TITLE</u>: Qualification of Deca Philippines for Bump Post-Test Production (Wafer saw, visual inspection, Tape and Reel)

### PROPOSED FIRST SHIP DATE: 12-May-2013

### AFFECTED CHANGE CATEGORY(S):

### FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or <todd.manes@onsemi.com>

**SAMPLES:** Contact your local ON Semiconductor Sales Office

#### ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or <Edmond.gallard@onsemi.com>

#### NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

### DESCRIPTION AND PURPOSE:

ON Semiconductor is pleased to announce a capacity expansion qualification of Deca, located in Laguna Park, Philippines, as an additional source for bump product post-test operations (wafer saw, visual inspection, Tape and Reel). These operations are currently performed at the ON Semiconductor facility located in Seremban, Malaysia. Upon expiration (or approval) of this FPCN, these operations may be performed at the ON Semiconductor, Malaysia facility or at the Deca facility in the Philippines.

Deca is certified to be compliant to ISO-9001 and ISO-14001.

All production operations that occur through the test operation will remain unchanged. No changes to wafer fab, bumping facility, or production test facility are being made. Only the operations that occur after test are affected by this notification.

No changes to Finished Goods or product packing will be made.

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### RELIABILITY DATA SUMMARY:

Visual Inspection and pick and place electronic map correlation have been performed between the existing production facility and Deca to ensure all rejects will continue to be detected and removed from production.

Visual inspection results and pick and place electronic maps have been confirmed to be equivalent between the two facilities.

A summary of the qualification results can be made available upon request.

### ELECTRICAL CHARACTERISTIC SUMMARY:

There are no changes to the electrical performance of products affected by this notification.

### CHANGED PART IDENTIFICATION:

Country of origin on the reel and packing labels will indicate Philippines for devices processed through Deca.

Country of origin on the reel and packing labels will indicate Malaysia for devices processed through the current production location of Seremban, Malaysia.

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### List of affected General Parts:

NCP1851FCCT1G NCP1852FCCT1G NCP2704FCCT1G NCP2705FCCT1G NCP2811AFCT1G NCP2811BFCT1G NCP2811BFCCT1G NCP2815AFCT2G NCP2815BFCT2G NCP2815BFCCT2G NCP2820FCT1G NCP2820AFCT2G NCP2823AFCT2G NCP2823BFCT2G NCP2823BFCT1G NCP2823AFCCT2G NCP2824FCT2G NCP2892AFCT2G NCP2892BFCT2G NCP2990FCT2G NCP2991FCT2G NCP2993FCT2G NCP6335DFCT1G NCP6335FFCT1G NCP6338FCT1G NCP6914AFCCLT1G NCP6914AFCAT1G NCP6914AFCBT1G NCP6914AFCDT1G NCP6924AFCET1G NCP6924AFCHT1G

### List of affected Customer Specific Parts:

NCP6335DFCCT1G NCP6335FFCCT1G